

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A molding method for manufacturing a resin molding by charging a resin composition ~~including~~ comprising fibrous filler (A) and crystalline resin (B) in molten state into a die by injection, ~~wherein~~ the resin composition ~~contains~~ comprising not less than 7 wt % to less than 30 wt % of the fibrous filler (A) and more than 70 wt % to not exceeding 93 wt % of the crystalline resin (B), the method comprising:

~~and that comprises the steps of;~~

[[(a)]] charging the resin composition in a molten state into the die ~~for shaping purpose~~ when a temperature of the die is in [[the]] a range of Vicat softening point -20°C ~~{the Vicat softening point minus 20°C}~~ of the resin (B) to less than a melting point of the resin (B), thereby shaping the resin composition, thereof, when the resin (B) is crystalline resin,

~~or charging the resin composition in molten state into the die for shaping purpose when a temperature of the die is in the range of [the Vicat softening point minus 20°C] to [the Vicat softening point plus 20°C] of the resin (B), when the resin (B) is non-crystalline resin;~~
and

after the resin composition is shaped, holding the temperature of the die for a predetermined time in a temperature range from a crystallization temperature -10°C to the crystallization temperature +10°C of the crystalline resin (B), and

[[(b)]] cooling down the die to a temperature which allows taking-out of a molded product, ~~after the shaping is performed.~~

Claim 2 (Withdrawn): A molding method for manufacturing a resin molding by extruding a resin composition including fibrous filler (A) and resin (B) to be converted into a molten parison, holding the parison within a die, and by blowing gas into the parison inside,

wherein the resin composition contains more than 7 wt % to less than 30 wt % of the fibrous filler (A) and more than 70 wt % to less than 93 wt % of the resin (B),

and that comprises the steps of;

(a) blowing gas into the parison inside for shaping purpose when a temperature of the die is in the range of [the Vicat softening point minus 20°C] of the resin (B) to less than a melting point thereof, when the resin (B) is crystalline resin,

or blowing a gas into the parison inside for shaping purpose when a temperature of the die is in the range of [the Vicat softening point minus 20°C] to [the Vicat softening point plus 20°C] of the resin (B), when the resin (B) is non-crystalline resin; and

(b) cooling down the die to temperature which allows taking-out of a molded product after the shaping is performed

Claims 3-10 (Canceled).

Claim 11 (Withdrawn): The molding method according to claim 2, wherein if the resin (B) is crystalline resin, after shaping of the resin composition is performed, a temperature of the die is held for preset period in the range of [crystallization temperature minus 15°C] to [crystallization temperature plus 10°C] of the resin (B).

Claim 12 (Currently Amended): The molding method according to claim 1, wherein shaping of the resin composition is performed when a temperature of the die is in the range of ~~[the Vicat softening temperature minus 10°C]~~ the Vicat softening temperature -10°C of the resin (B) to the melting point -10°C of ~~[melting point minus 10°C]~~, when the resin (B) is crystalline resin;

~~or performed when a temperature of the die is in the range of [the Vicat softening temperature minus 10°C] to [the Vicat softening temperature plus 10°C] of the resin (B), when the resin (B) is non-crystalline resin.~~

Claim 13 (Withdrawn): The molding method according to claim 2, wherein shaping of the resin composition is performed when a temperature of the die is in the range of [the Vicat softening temperature minus 10°C] of the resin (B) to [melting point minus 10°C], when the resin (B) is crystalline resin,

or performed when a temperature of the die is in the range of [the Vicat softening temperature minus 10°C] to [the Vicat softening temperature plus 10°C] of the resin (B), when the resin (B) is non-crystalline resin.

Claim 14 (Currently Amended): The molding method according to claim 1, wherein ~~after shaping of the resin composition is performed, a temperature of the die is held for preset period in the~~ temperature range for said holding is from the ~~of [crystallization temperature minus 10°C] crystallization temperature -10°C to [crystallization temperature] the crystallization temperature~~ of the resin (B), ~~when the resin (B) is crystalline resin.~~

Claim 15 (Withdrawn): The molding method according to claim 2, wherein after shaping of the resin composition is performed, a temperature of the die is held for preset period in the range of [crystallization temperature minus 10°C] to [crystallization temperature] of the resin (B), when the resin (B) is crystalline resin.

Claim 16 (Currently Amended): The molding method according to claim 1, wherein the resin composition ~~contains not less than~~ comprises 10 wt % or more and to not exceeding ~~to~~ 25 wt % or less of the fibrous filler (A).

Claim 17 (Withdrawn): The molding method according to claim 2, wherein the resin composition contains not less than 10 wt % to not exceeding to 25 wt % of the fibrous filler (A).

Claim 18 (Previously Presented): A resin molding manufactured by the molding method of claim 1.

Claim 19 (Withdrawn): A resin molding manufactured by the molding method of claim 2.

Claim 20 (Withdrawn): A resin molding containing not less than 7 wt % to less than 30 wt % of a fibrous fiber (A) and more than 70 wt % to not exceeding 93 wt % of a resin (B), wherein surface roughness is less than 5 μm and an image representation of 1 mm square rectangular frame reflected on the surface can be discriminated.

Claim 21 (Withdrawn): A resin molding having an emboss on the surface and containing not less than 7 wt % to less than 30 wt % of a fibrous fiber (A) and more than 70 wt % to not exceeding 93 wt % of a resin (B), and is characterized by either one of the following 1 or 2.

(1) Die transcription rate is more than 90% for such a case where emboss is provided over whole surface of a resin molding;

(2) Die transcription rate is more than 90% and surface roughness of such an area where there is no emboss is less than 5 μm for such a case where emboss is provided in part of a resin molding.

Claim 22 (Withdrawn): The resin molding according to claim 20, wherein the resin composition contains not less than 10 wt % to not exceeding to 25 wt % of the fibrous filler (A).

Claim 23 (Withdrawn): The resin molding according to claim 21, wherein the resin composition contains not less than 10 wt % to not exceeding to 25 wt % of the fibrous filler (A).

Claim 24 (New): The resin molding method according to claim 1, wherein the crystalline resin is polyolefin resin.

Claim 25 (New): The resin molding method according to claim 1, wherein the predetermined time is from 10 to 300 seconds.

Claim 26 (New): The resin molding method according to claim 1, wherein the predetermined time is from 30 to 200 seconds.

Claim 27 (New): The resin molding method according to claim 1, wherein the fibrous filler (A) has a fiber diameter of less than 25 μm .